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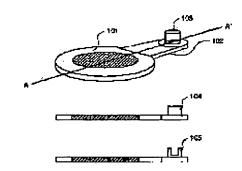
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(54) MULTIALYER WIRING BOARD, PRODUCTION OF THE BOARD AND SEMICONDUCTOR DEVICE USING THE BOARD

(57)Abstract:

PURPOSE: To obtain a structure for forming high density wiring by extending a land present on the circumferential fringe of a filled plated through hole and forming a via for connecting with an upper or lower wiring layer in the surface at the extended land part.

CONSTITUTION: A land 101 formed on the circumferential fringe of a filled plated through hole in a double side printed wiring board is partially extended 102. A via 103 for connection with the wiring layer in a sequentially laminated thin film layer on the outside is formed at the forward end of the extended land part 102. A stud via 104 or a conformal via 105 may be employed and the stud via 104 is preferably employed because a finer via, having not a truncated conical profile but a columnar profile, can be formed.



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